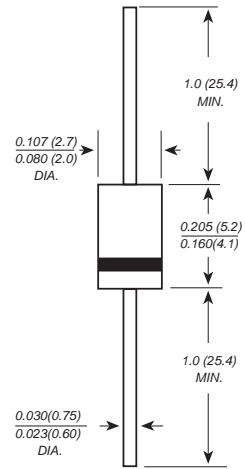


Features

- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- Glass passivated junction chip
- Low reverse leakage
- High forward surge current capability
- High temperature soldering guaranteed
260°C/10 seconds at terminals

DO-41



Dimensions in inches and (millimeters)

Mechanical Data

- Case** : Molded plastic body
- Terminals** : Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity** : Polarity symbol marking on body
- Mounting Position** : Any
- Weight** : 0.0088 ounce, 0.25 grams

Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	UF4001G	UF4002G	UF4003G	UF4004G	UF4005G	UF4006G	UF4007G	UNITS
Maximum repetitive peak reverse voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current at T _L =100°C	I _(AV)	1.0							A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	I _{FSM}	30.0							A
Maximum instantaneous forward voltage at 1.0A	V _F	1.0		1.4		1.7		V	
Maximum DC reverse current T _A =25°C at rated DC blocking voltage T _A =125°C	I _R	2.0 200							uA
Maximum reverse recovery time(Note 1)	T _{rr}	50				75			ns
Typical junction capacitance (Note2)	C _J	25.0							pF
Typical thermal resistance	R _{qJA}	65.0							°C/W
Operating junction and storage temperature range	T _J , T _{STG}	-55 to +150							°C

Note: 1.Reverse recovery time test condition: I_F=0.5A I_R=1.0A I_{rr}=0.25A
2.Measured at 1MHz and applied reverse voltage of 4.0V D.C.

Ratings And Characteristic Curves

FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT

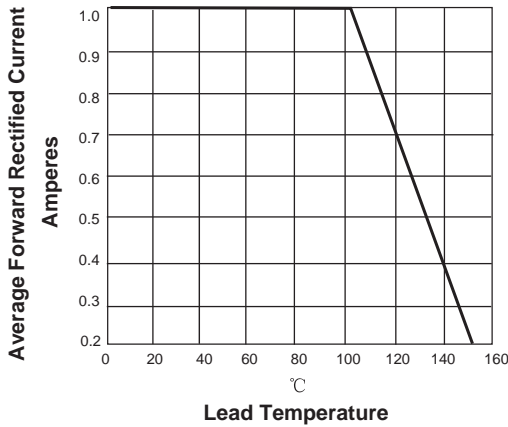


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PER LEG

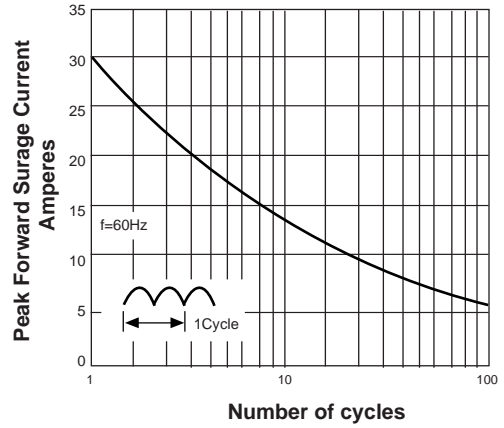


FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS

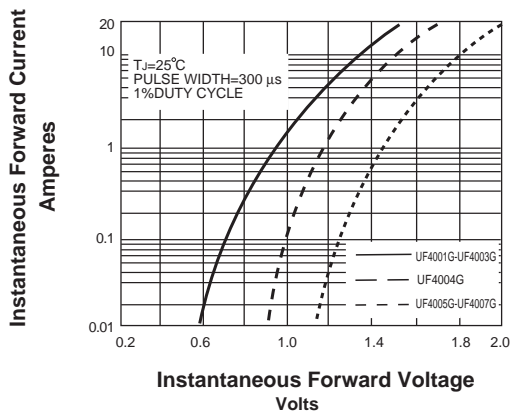
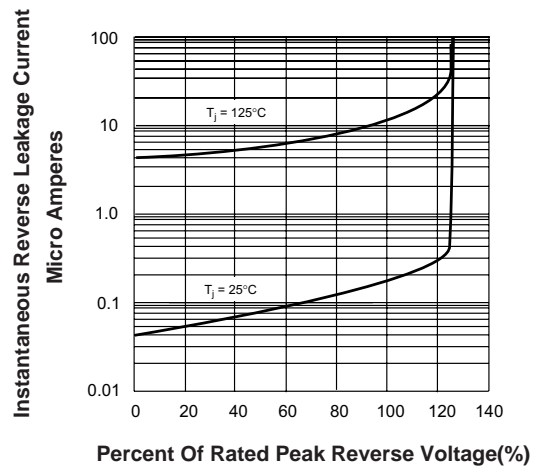
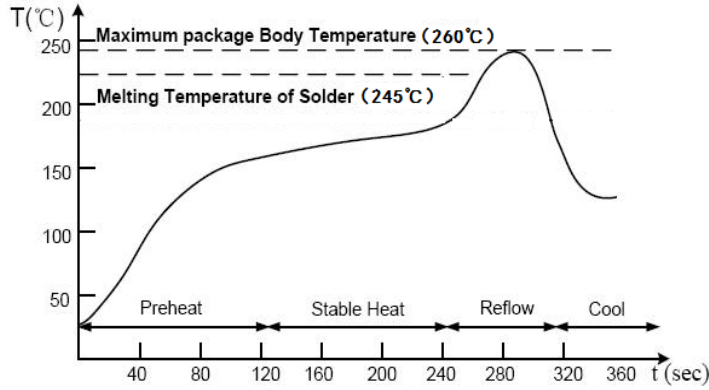


FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS



Suggested Soldering Temperature Profile

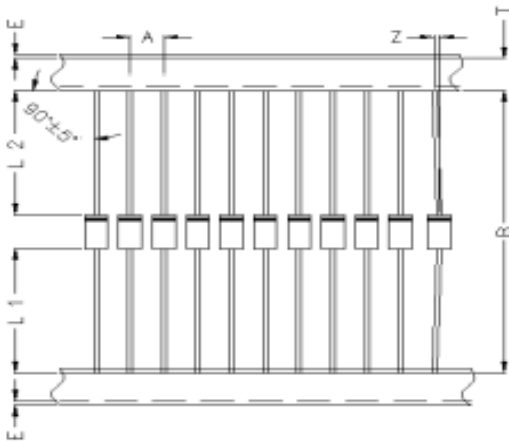


Note

- Recommended reflow methods: IR, vapor phase oven, hot air oven, wave solder.
- The device can be exposed to a maximum temperature of 260°C for 10 seconds.
- Devices can be cleaned using standard industry methods and solvents.
- If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Package Information

Taping Specifications



Item	Symbol	Specifications(mm)
Component Pitch	A	5.0±0.5
Inner Tape Pitch	B	52.4±1.5
Component alignment	Z	1.2 Max
Tape width	T	6.0±0.5
Exposed adhesive	E	0.8 Max
Body eccentricity	L1-L2	1.0 Max

Ammunition Package Specifications

Package	Inner Box Size (mm)	QTY/Box (Kpcs)	Carton Size (mm)	Q'TY/Carton (Kpcs)
DO - 41	255*150*75	5	420*276*312	50